

THE COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 2023

Packet No. TSMC98-403

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: SHIH-SHIUNG CHEU, YEA-DEAN SHEU AND CHIH-HENG SHEN

A COST EFFECTIVE POLYIMIDE PROCESS TO SOLVE PASSIVATION EXTRUSION OR DAMAGE AND SOG
DELAMINATES

Enclosed are:

- ☒ 6 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to Taiwan Semiconductor Manufacturing Company
- ☐ An associate power of attorney

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 760.
TOTAL CLAIMS	30 -20=	10	x 18 =	\$ 180.
INDEP CLAIMS	2 -3=	0	x 78 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 940.
			ASSIGNMENT	\$40.
			TOTAL	\$ 980.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 980. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees; associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR \$1.16.
- ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

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